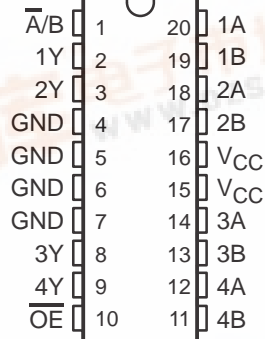


QUADRUPLE 2-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER WITH 3-STATE OUTPUTS

SCAS049C – MARCH 1989 – REVISED MAY 2004

- 3-State Outputs Interface Directly With System Bus
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- 500-mA Typical Latch-Up Immunity at 125°C
- Provides Bus Interface From Multiple Sources in High-Performance Systems

DB, DW, N, OR PW PACKAGE
(TOP VIEW)

description/ordering information

This device is designed to multiplex signals from 4-bit data sources to four output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable (\overline{OE}) input is at a high logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	74AC11257N	74AC11257N
		Tube	74AC11257DW	AC11257
	SOIC – DW	Tape and reel	74AC11257DWR	
		Tape and reel	74AC11257DBR	AE257
	SSOP – DB	Tape and reel	74AC11257PW	AE257
		Tape and reel	74AC11257PWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

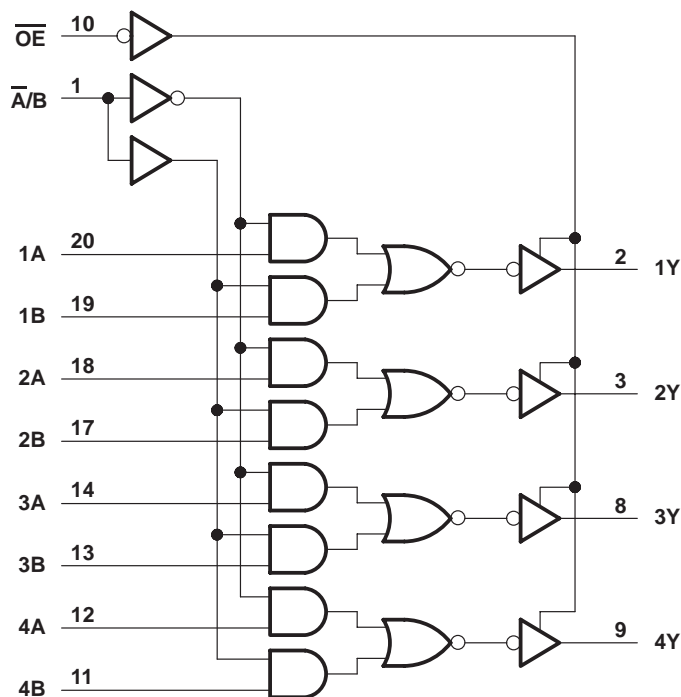
\overline{OE}	SELECT $\overline{A/B}$	INPUTS DATA		OUTPUT Y
		A	B	
H	X	X	X	Z
L	L	L	X	L
L	L	H	X	H
L	H	X	L	L
L	H	X	H	H

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QUADRUPLE 2-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER WITH 3-STATE OUTPUTS

SCAS049C – MARCH 1989 – REVISED MAY 2004

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	−0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	70°C/W
DW package	58°C/W
N package	60°C/W
PW package	83°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

-
2. The package thermal impedance is calculated in accordance with JESD 51-7.

74AC11257
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER
WITH 3-STATE OUTPUTS

SCAS049C – MARCH 1989 – REVISED MAY 2004

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	3	5	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 3\text{ V}$	2.1		V
		$V_{CC} = 4.5\text{ V}$	3.15		
		$V_{CC} = 5.5\text{ V}$	3.85		
V_{IL}	Low-level input voltage	$V_{CC} = 3\text{ V}$		0.9	V
		$V_{CC} = 4.5\text{ V}$		1.35	
		$V_{CC} = 5.5\text{ V}$		1.65	
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 3\text{ V}$		–4	mA
		$V_{CC} = 4.5\text{ V}$		–24	
		$V_{CC} = 5.5\text{ V}$		–24	
I_{OL}	Low-level output current	$V_{CC} = 3\text{ V}$		12	mA
		$V_{CC} = 4.5\text{ V}$		24	
		$V_{CC} = 5.5\text{ V}$		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T_A	Operating free-air temperature	–40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	$I_{OH} = -50\text{ }\mu\text{A}$	3 V	2.9			2.9		V
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
	$I_{OH} = -4\text{ mA}$	3 V	2.58			2.48		
		4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	$I_{OH} = -75\text{ mA}^\dagger$	5.5 V				3.85		
V_{OL}	$I_{OL} = 50\text{ }\mu\text{A}$	3 V			0.1		0.1	V
		4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
	$I_{OL} = 12\text{ mA}$	3 V			0.36		0.44	
		4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	$I_{OL} = 75\text{ mA}^\dagger$	5.5 V					1.65	
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			± 0.5		± 5	μA
I_I	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		± 1	μA
I_{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μA
C_i	$V_I = V_{CC}$ or GND	5 V		3.5				pF
C_o	$V_O = V_{CC}$ or GND	5.5 V		8				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

74AC11257**QUADRUPLE 2-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER
WITH 3-STATE OUTPUTS**

SCAS049C – MARCH 1989 – REVISED MAY 2004

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	Y	1.5	5.6	8.1	1.5	8.9	ns
t_{PHL}			1.5	6.2	9	1.5	10.1	
t_{PLH}	\bar{A}/B	Any Y	1.5	6.1	9.2	1.5	10.2	ns
t_{PHL}			1.5	6.6	10	1.5	11.2	
t_{PZH}	\overline{OE}	Any Y	1.5	5.6	8.2	1.5	9.1	ns
t_{PZL}			1.5	7.5	10.4	1.5	11.8	
t_{PHZ}	\overline{OE}	Any Y	1.5	5.6	7.6	1.5	8.3	ns
t_{PLZ}			1.5	6.2	8.8	1.5	9.6	

switching characteristics, over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	Y	1.5	3.6	5.8	1.5	6.4	ns
t_{PHL}			1.5	4.1	6.5	1.5	7.2	
t_{PLH}	\bar{A}/B	Any Y	1.5	4	6.5	1.5	7.2	ns
t_{PHL}			1.5	4.4	7.1	1.5	7.9	
t_{PZH}	\overline{OE}	Any Y	1.5	3.8	5.9	1.5	6.5	ns
t_{PZL}			1.5	5	7.6	1.5	8.6	
t_{PHZ}	\overline{OE}	Any Y	1.5	4.5	6.4	1.5	7.6	ns
t_{PLZ}			1.5	4.8	6.9	1.5	7.6	

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

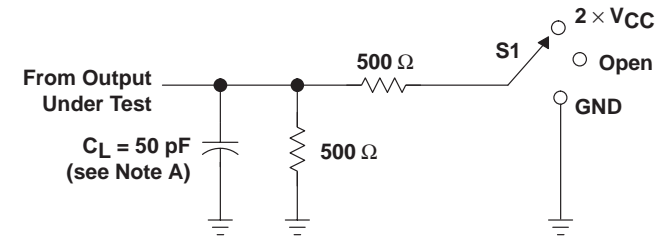
PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	$C_L = 50\text{ pF}$, $f = 1\text{ MHz}$	37	pF
		Outputs disabled		11	

74AC11257

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER WITH 3-STATE OUTPUTS

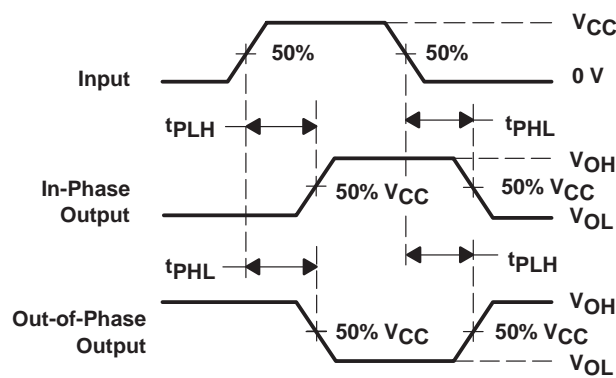
SCAS049C – MARCH 1989 – REVISED MAY 2004

PARAMETER MEASUREMENT INFORMATION

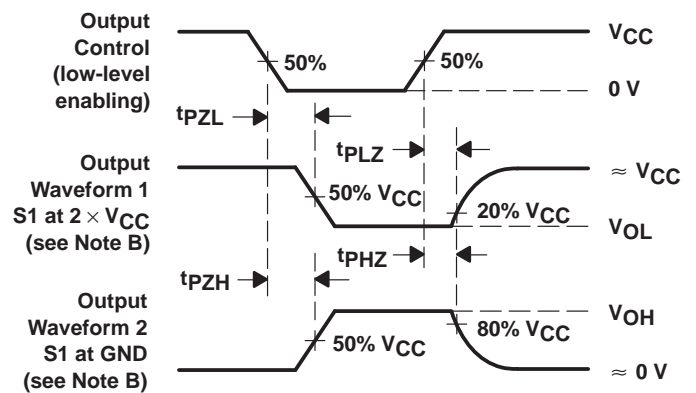


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
 - D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AC11257DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11257DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11257DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11257DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11257DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11257DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11257N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11257NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11257PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11257PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11257PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11257PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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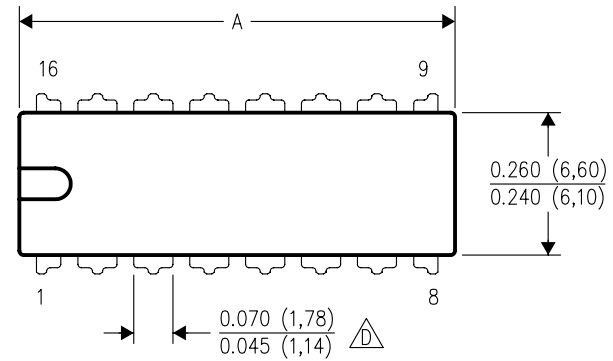
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MECHANICAL DATA

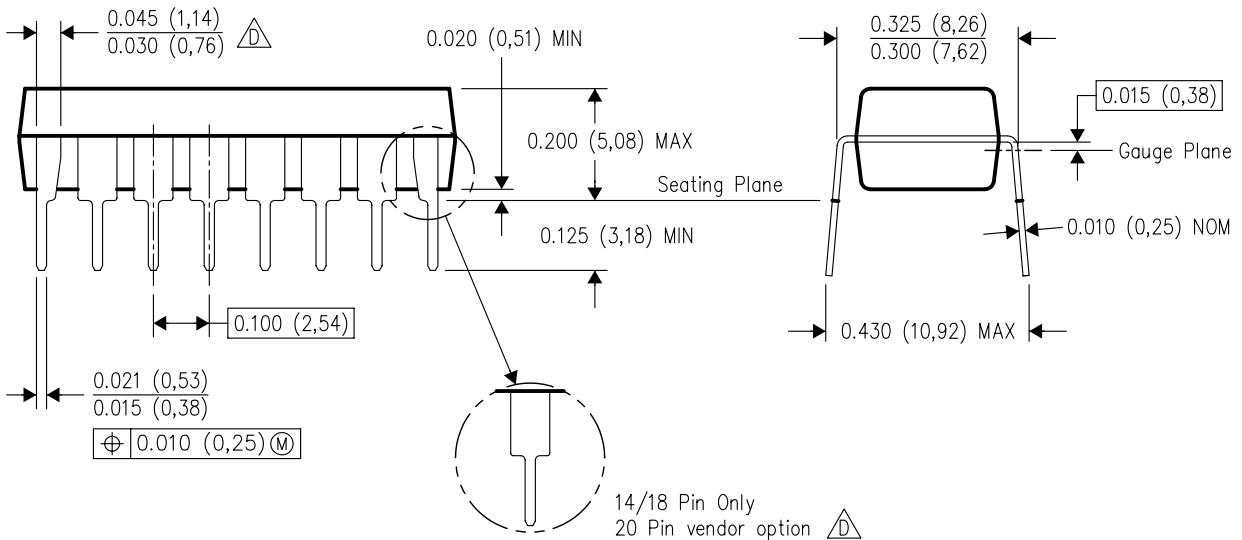
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



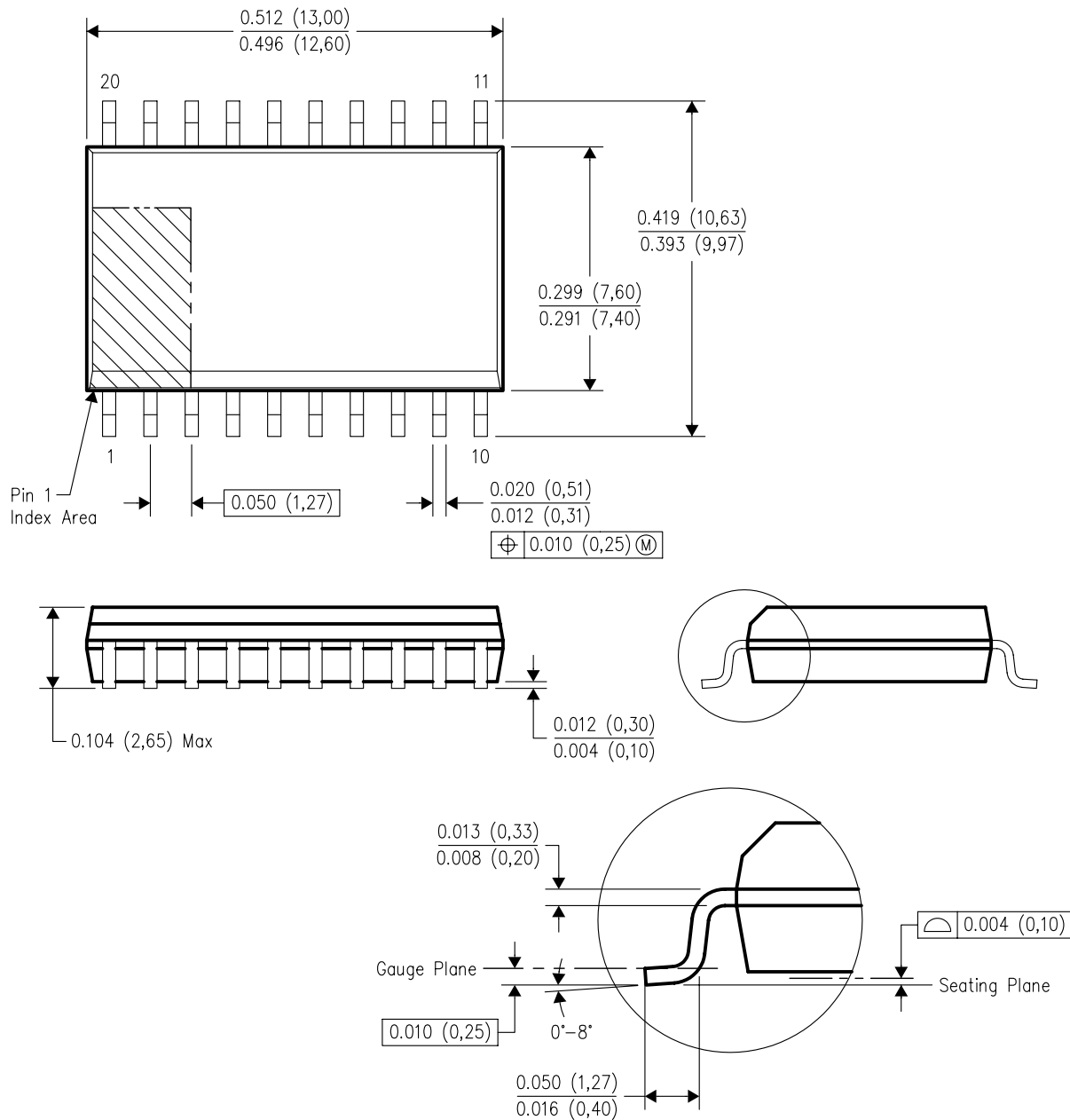
4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



4040000-4/F 06/2004

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

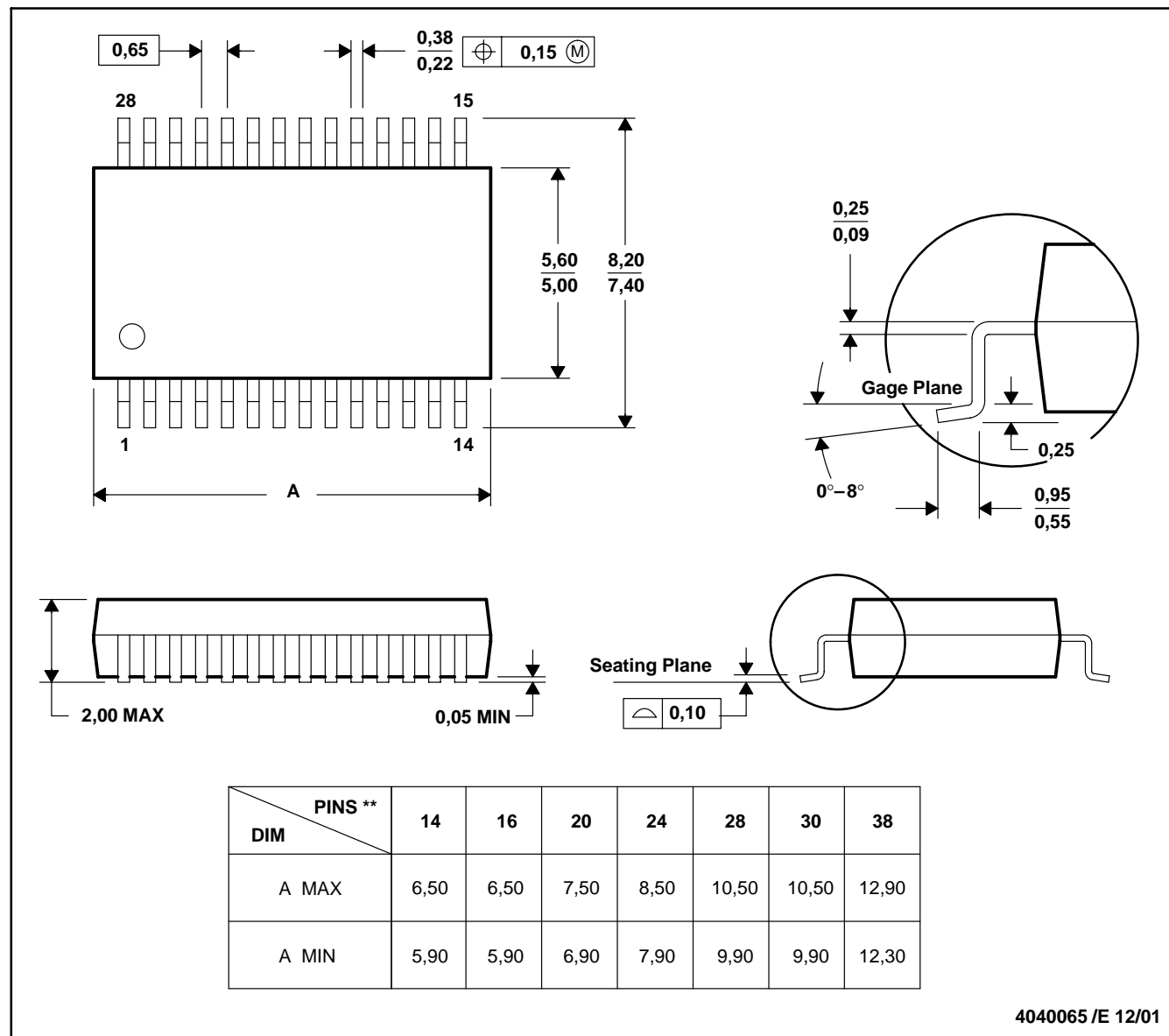
MECHANICAL DATA

MSS0002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

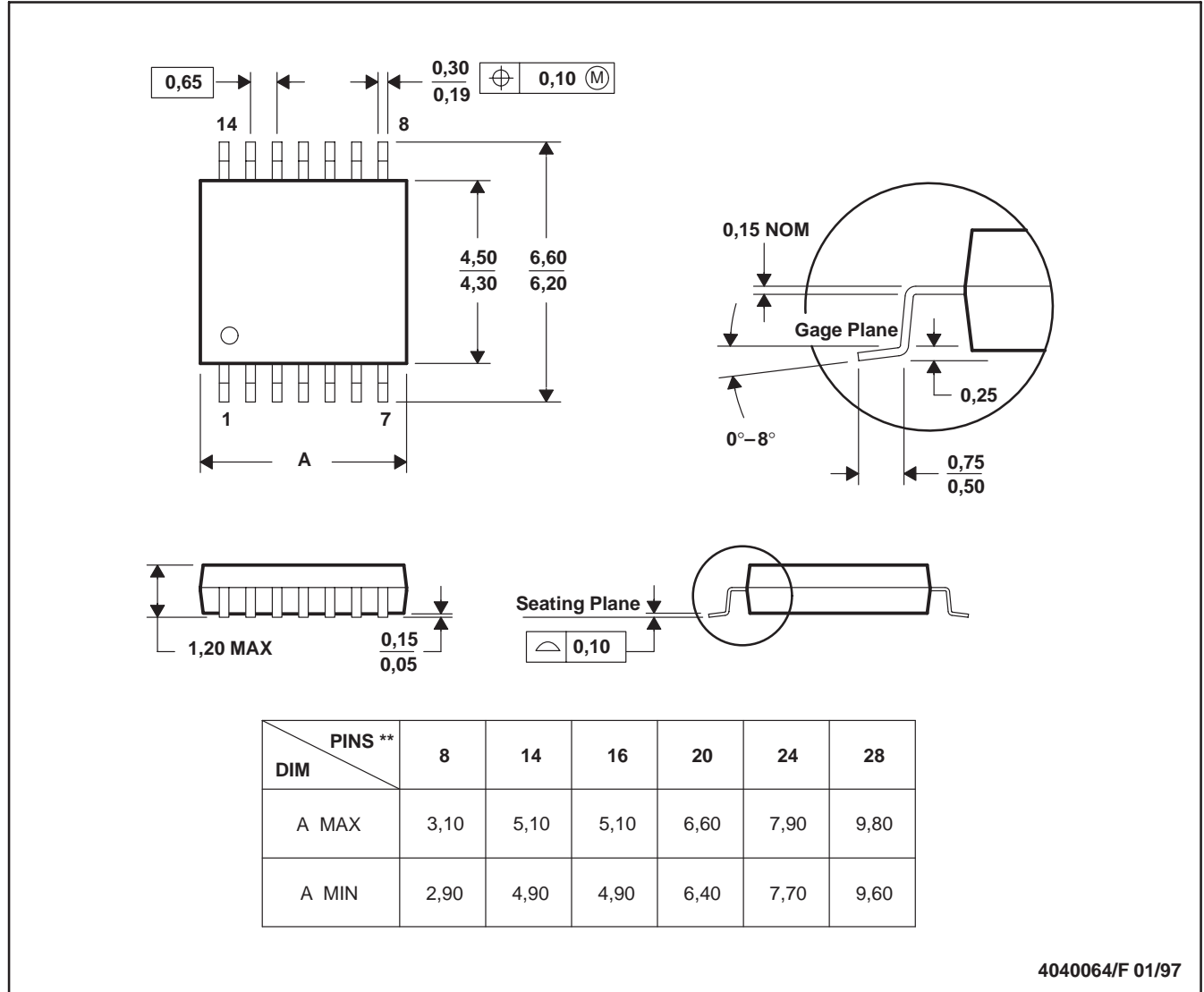
MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265